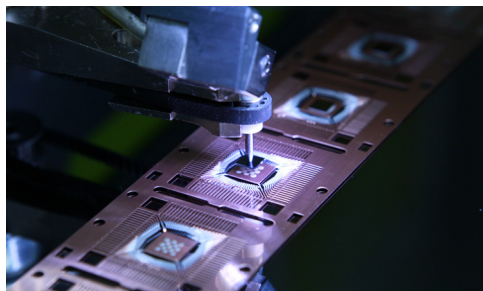


Pressure-less Silver Sintering Paste



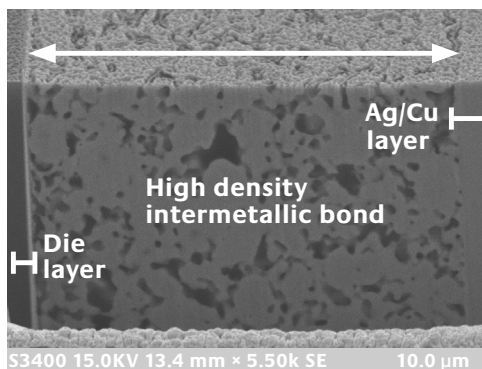
APPLICATIONS

- ▶ High power device such as IGBT modules
- ▶ High performance LED packaging
- ▶ Alternative for high Pb solder alloys

FEATURES

- ▶ Outstanding thermal conductivity
- ▶ Outstanding electrical performance
- ▶ Pressureless sintering capability
- ▶ Outstanding interface reliability
- ▶ Outstanding workability (dispensable)
- ▶ Low temperature sintering capability

X-section by FIB



General properties

Item	Data	Appendix
Cure condition	200°C 90 min.	No pressure, in air
Viscosity	26 Pa*s	E type viscometer 0.5 rpm
Elastic modulus	21.6 GPa	Tensile test
Coefficient of thermal expansion	20 ppm	TMA method
Thermal conductivity	> 200 W/m*K	Laser flash method
Volume resistance	4μΩ	Four point probe method
Shear strength at 260°C	> 30 MPa	Die backside Au/Ag plated CU LF
Applicable adhered	Ag, Au, Bare Cu	-